



OshPark 4 layer process:

Copper:

Spec	Value
Copper Layers	4
Copper Weight	1oz outer
1/2oz inner	
Trace Spacing	5mil (0.127mm)
Trace Width	5mil (0.127mm)
Annular Ring	4mil (0.1016mm)
Board Edge Keepout	15mil (0.381) from nominal board edge
Via Plating Thickness	1mil (0.0254mm)

Layer Stackup:

Thickness	Type	Tolerance
1mil (0.0254mm)	silkscreen	+/-0.2mil (0.00508mm)
1 mil (0.0254mm)	solder resist	+/-0.2mil (0.0051mm)
1.4 mil (0.0356mm)	1 oz copper	
6.7 mil (0.1702mm)	FR408 prepreg	+/-0.67mil (0.017mm)
0.7 mil (0.0178mm)	0.5 oz copper	
47 mil (1.1938mm)	FR408 core	+/-4.7mil (0.1194mm)
0.7 mil (0.0178mm)	0.5 oz copper	
6.7 mil (0.1702mm)	FR408 prepreg	+/-0.67mil (0.017mm)
1.4 mil (0.0356mm)	1 oz copper	
1 mil (0.0254mm)	solder resist	+/-0.2mil (0.0051mm)
1mil (0.0254mm)	silkscreen	+/-0.2mil (0.00508mm)

Drill Spec	Type	Note
Minimum Hole size	10 mil (0.254mm)	Holes belows this size will be rounded up
Maximum Drilled Hole Size	260 mil (6.604mm)	Holes exceeding this size will be milled
Annular Ring	4 mil (0.1016mm)	
Via Plating Thickness	1 mil (0.0254mm)	
Fabricated Hole Size Tolerance	+/-2.5mil max (0.0635mm)	+/-1 mil typical (0.0254mm)
Fabricated Hole Position Tolerance	+/-2.5mil max (0.0635mm)	+/-1 mil typical (0.0254mm)

Sheet:		
File: portalgun-display.kicad_pcb		
Title:		
Size: A4	Date:	Rev:
KiCad E.D.A. kicad 5.1.9-73d0e3b20d88ubuntu20.04.1		Id: 1/1